

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants :Masaru SHIRAI et al. Group Art Unit : 1725
Appl. No. : 10/598,142 Examiner :
Filed : August 18, 2006 Confirmation No. : 1550
For : HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING
METHOD AND APPARATUS

RESPONSE TO REQUIREMENT FOR RESTRICTION

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop **AMENDMENT**
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir :

This paper responds to the Requirement for Restriction under 35 U.S.C. § 121 and 35 U.S.C. § 372 mailed from the U.S. Patent and Trademark Office on February 9, 2009. Inasmuch as the Office Action sets a one-month shortened statutory period for response, to end March 9, 2009, no fee is believed due at this time. However, the Office is authorized to charge any required fee to Deposit Account No. 19-0089.

Remarks, including an election without traverse, begin on page 2 of this paper.